

Title (en)

Opto-electronic hybrid integration platform, optical sub-module, opto-electronic hybrid integration circuit, and process for fabricating platform

Title (de)

Optoelektronische Hybridintegrationsplattform, optisches Untermodul, optoelektronische hybridintegrierte Schaltung, und Herstellungsverfahren der Plattform

Title (fr)

Plate-forme pour intégration optoélectronique hybride, sous-module optique, circuit intégré de type hybride optélectronique, et procédé de fabrication de la plate-forme

Publication

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Application

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Priority

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- JP 30657893 A 19931207
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- JP 14822294 A 19940629

Abstract (en)

[origin: EP0638829A1] An opto-electronic hybrid integrated circuit of the present invention satisfy a low-loss optical waveguide function, an optical bench function and a high-frequency electrical wiring function. The circuit includes a silicon substrate (1), an optical waveguide part (I) arranged in a recess of the substrate (1), and an optical device mounting part (II) formed on a protrusion (52) of the substrate (1). An optical device (37) is mounted on an optical sub-module (44). This sub-module (44) is placed on the protrusion (52). An electrical wiring part is disposed on another protrusion 35 of the substrate (1). <IMAGE>

IPC 1-7

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IPC 8 full level

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